AMENDMENTS TO THE CLAIMS

1-22. (cancelled)

- 5 23. (currently amended): A light emitting diode having an adhesive layer and a reflective layer, comprising at least:
 - a substrate;
 - a reflective layer formed over the substrate;
 - a first reaction layer formed over said reflective layer;
- a transparent adhesive layer formed over said first reaction layer;
 - a second reaction layer formed over said transparent adhesive layer;
- and an LED stack formed over said second reaction layer;

 wherein at least one of the first and second reaction layers is formed to enhance an adhesion provided by the transparent adhesive layer.
- 24. (original): A light emitting diode having an adhesive layer
 20 and a reflective layer according to claim 23, further
 comprising a transparent conductive layer between said
 second reaction layer and said LED stack.
- 25. (original): A light emitting diode having an adhesive layerand a reflective layer according to claim 23, wherein said reflective layer is a reflective metal layer.
 - 26. (cancelled)
- 30 27. (previously presented): A light emitting diode having an adhesive layer and a reflective layer according to claim 25, wherein said reflective metal layer comprises at least

a material selected from the group consisting of In, Sn, Al, Au, Pt, Zn, Ag, Ti, Pb, Pd, Ge, Cu, AuBe, AuGe, Ni, PbSn, and AuZn.

5 28. (cancelled)

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- 29. (previously presented): A light emitting diode having an adhesive layer and a reflective layer according to claim 23, wherein said transparent adhesive layer comprises at least a material selected from the group consisting of polyimide (PI), benzocyclobutene (BCB), and perfluorocyclobutane (PFCB).
- 30. (previously presented): A light emitting diode having an adhesive layer and a reflective layer according to claim 23, wherein said first reaction layer or said second reaction layer comprises at least a material selected from the group consisting of SiNx, Ti, and Cr.

20 31-43. (cancelled)

- 44. (currently amended): A light emitting diode having an adhesive layer and a reflective layer, comprising at least: a reflective means;
- a first reaction layer formed over said reflective means; a transparent adhesive layer formed over said first reaction layer;
 - a second reaction layer formed over said transparent adhesive layer; and
- an LED stack formed over said second reaction layer;
 wherein at least one the first and second reaction layers
 is formed to enhance an adhesion provided by the transparent

adhesive layer.

- 45. (new): A light emitting diode having an adhesive layer and a reflective layer, comprising at least:
- 5 a substrate;

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- a reflective layer disposed on the substrate;
- a first reaction layer formed on said reflective layer;
- a transparent adhesive layer formed directly on said first reaction layer, said first reaction layer adhering to the transparent adhesive layer;
- a second reaction layer formed directly on said transparent adhesive layer, said second reaction layer adhering to the transparent adhesive layer; and an LED stack formed over said second reaction layer.
- 46. (new): A light emitting diode having an adhesive layer and a reflective layer according to claim 45, wherein bonding forces between the first reaction layer and the transparent adhesive layer and between the second reaction layer and the transparent adhesive layer are greater than bonding forces between materials of the first reflective layer and the transparent adhesive layer and between materials of the LED stack and the transparent adhesive layer.
- 47. (new): A light emitting diode having an adhesive layer and a reflective layer according to claim 45, further comprising a transparent conductive layer between said second reaction layer and said LED stack.
- 48. (new): A light emitting diode having an adhesive layer and a reflective layer according to claim 45, wherein said

reflective layer is a reflective metal layer.

- 49. (new): A light emitting diode having an adhesive layer and a reflective layer according to claim 48, wherein said reflective metal layer comprises at least a material selected from the group consisting of In, Sn, Al, Au, Pt, Zn, Ag, Ti, Pb, Pd, Ge, Cu, AuBe, AuGe, Ni, PbSn, and AuZn.
- 50. (new): A light emitting diode having an adhesive layer and a reflective layer according to claim 45, wherein said transparent adhesive layer comprises at least a material selected from the group consisting of polyimide (PI), benzocyclobutene (BCB), and perfluorocyclobutane (PFCB).
- 15 51. (new): A light emitting diode having an adhesive layer and a reflective layer according to claim 45, wherein said first reaction layer or said second reaction layer comprises at least a material selected from the group consisting of SiNx, Ti, and Cr.

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